| ASSOCIATION CONNECTING<br>LECTRONICS INDUSTRIES®<br>International and Pan- | C, Bannockb  | ourn, Illinois. A | Il rights reserved u ntions. | nder both     | This docum<br>level parts,   | ent is a declarati<br>the declaration e | on of the sub<br>ncompasses a | stances wi<br>all lower le | ithin the manufacture<br>evel materials for wh | er listed i<br>hich the r       | tem. Note: if<br>nanufacturer | the item is an as has engineering | sembly with lower responsibility. |
|--|--|-------------------|------------------------------|---------------|--|---|-------------------------------|----------------------------|--|---------------------------------|-------------------------------|-----------------------------------|-----------------------------------|
|  | IPC Web Site for Information on IPC-1752 Standard Form<br>http://www.ipc.org/IPC-175x Dist |                   |                              |               | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Inform |   |                               |                            |  | lfg Informati                   | on                            |                                   |                                   |
| Supplier Information   |  |                   |                              |               |  |   |                               |                            |  |                                 |                               |                                   |                                   |
| Company name* Co   |  |                   | Company unique ID            |               |  | Unique ID Authority                     |                               |                            |  | Response Date*                  |                               |                                   |                                   |
| onsemi   |  |                   |                              |               |  | ,<br>I                                  |                               |                            |  | 2025-06-07                      |                               |                                   |                                   |
| Contact Name Title - Contact   |  |                   | t                            |               |  | Phone - Contact*                        |                               |                            |  | Email - Contact*                |                               |                                   |                                   |
| Product-Env-Stewards Product Env   |  |                   | et Enviro Compliance         |               |  | NA                                      |                               |                            |  | Product-Env-Stewards@onsemi.com |                               |                                   |                                   |
| Authorized Representative* Title - Rep                                     |  |                   | Representative               |               |  | Phone - Representative*                 |                               |                            | Email - Representative*                        |                                 |                               |                                   |                                   |
| Product-Env-Stewards Product F   |  |                   | oduct Enviro Compliance      |               |  | NA                                      |                               |                            |  | Product-Env-Stewards@onsemi.com |                               |                                   |                                   |
| Requester Item Number  | Mfr Item Number  |                   | umber Mfr Item Name          |               |  | Effective Date                          | Version                       | Ma                         | anufacturing Site                              |                                 | Weight*                       | UOM                               | Unit Type                         |
|  | MMSZ1  | 2T1G              | ZEN SOD123 REG 0.5W 12V      |               |  | 2025-06-07                              |                               | CN                         | CN1  |                                 | 11.525                        | mg                                | Each                              |
| Manufacturing Proccess Informat  | ion  |                   |                              |               |  |   |                               |                            |  |                                 |                               |                                   |                                   |
| Terminal Plating / Grid Array Mat  | Ferminal Plating / Grid Array Material Terminal Base                                       |                   | Alloy J                      | J-STD-020 MSI | L Rating   | Peak Proc                               | ess Body Ten                  | nperature                  | Max Time at Peak                               | Tempera                         | ture Numb                     | er of Reflow Cy                   | eles                              |
| Matte Tin (Sn) - annealed CU Alloy   |  | 1                 | 1                            |               | 260  | 0                                       | C                             | 30                         | secor  | nds 3                           |                               |                                   |                                   |
| Comments   |  |                   |                              |               |  |   |                               |                            |  |                                 |                               |                                   |                                   |
| level 1 - maximum time at peak temperatu                                   | e during sol   | dering is 10-3    | 0 seconds                    |               |  |   |                               |                            |  |                                 |                               |                                   |                                   |
| For more information regarding material of                                 | omposition   | please refer to   | page 3                       |               |  |   |                               |                            |  |                                 |                               |                                   |                                   |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead<br>b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl<br>nthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance  | CAS         | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|-------------|--------|--------|-----------------|
| Die                  | 0.88   | mg              | Supplier | Silicon (Si)   | 7440-21-3   |        | 0.88   | mg              |
| Lead Frame           | 3.19   | mg              | В        | Nickel (Ni)  | 7440-02-0   |        | 1.158  | mg              |
|                      |        |                 | Supplier | Iron (Fe)  | 7439-89-6   |        | 1.6014 | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8   |        | 0.4306 | mg              |
| Mold Compound-Black  | 6.51   | mg              | Supplier | Boron zinc hydroxide oxide                             | 138265-88-0 |        | 0.1953 | mg              |
|                      |        |                 | Supplier | Zinc Monoxide (ZnO)                                    | 1314-13-2   |        | 0.0325 | mg              |
|                      |        |                 | Supplier | 2,4,6-triamino-s-triazincompd.withs-<br>triazine-triol | 37640-57-6  |        | 0.1953 | mg              |
|                      |        |                 | Supplier | Silica Amorphous (SiO2)                                | 7631-86-9   |        | 5.208  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)                                       | 1333-86-4   |        | 0.0651 | mg              |
|                      |        |                 | Supplier | Ortho-Cresol Novolac Resin                             | 29690-82-2  |        | 0.5208 | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)                               | 9003-35-4   |        | 0.2929 | mg              |
| Plating              | 0.8    | mg              | Supplier | Tin (Sn)   | 7440-31-5   |        | 0.8    | mg              |
| Wire Bond            | 0.145  | mg              | Supplier | Palladium (Pd)   | 7440-05-3   |        | 0.0019 | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8   |        | 0.1431 | mg              |